

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

MSAZ5825-01F

Product specification

Features

- 120 W peak pulse power per line t_P (= 8/20 μ s)
- DFN1006-2L package
- Replacement for MLV(0402)
- Bidirectional configurations
- Response time is typically < 1ns
- Low clamping voltage
- RoHS compliant
- Transient protection for data lines to
- IEC61000-4-2(ESD) \pm 30KV(air), \pm 30KV(contact);
IEC61000-4-4 (EFT) 40A (5/50ns)


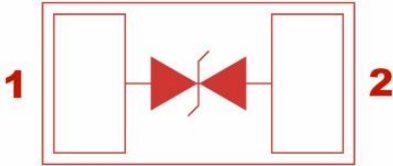
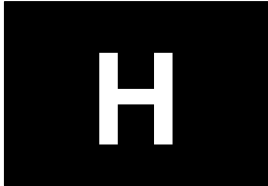
Applications

- Cellular phones
- Portable devices
- Digital cameras
- Power supplies

Mechanical Characteristics

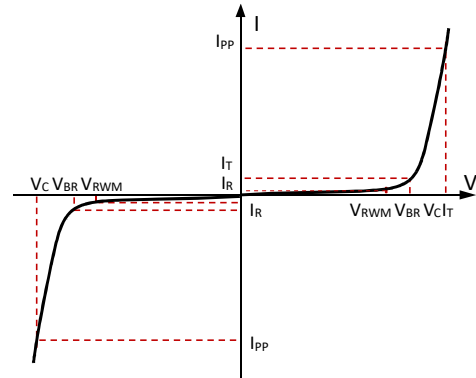
- Mounting position: Any
- Qualified max reflow temperature:260℃
- Device meets MSL 1 requirements
- DFN1006-2L without plating

Reference News

PACKAGE OUTLINE	PIN Configuration	Marking
		
DFN-1006		

Electronics Parameter

Symbol	Parameter
V_{RWM}	Peak Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
P_{PP}	Peak Pulse Power
C_J	Junction Capacitance



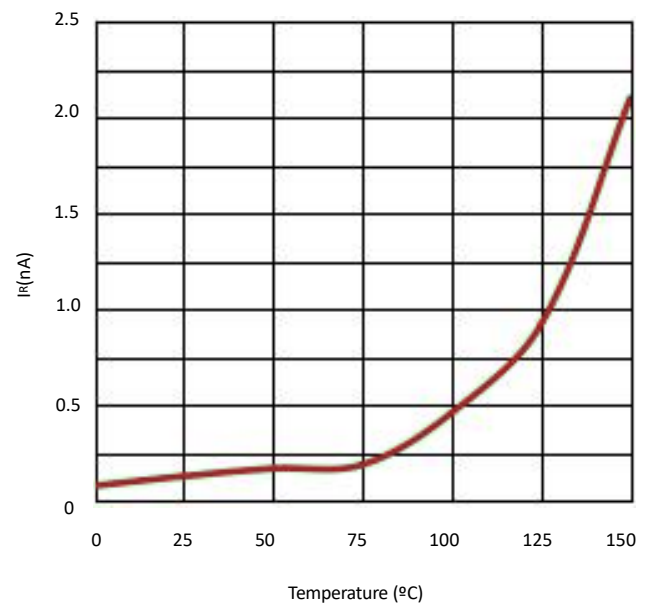
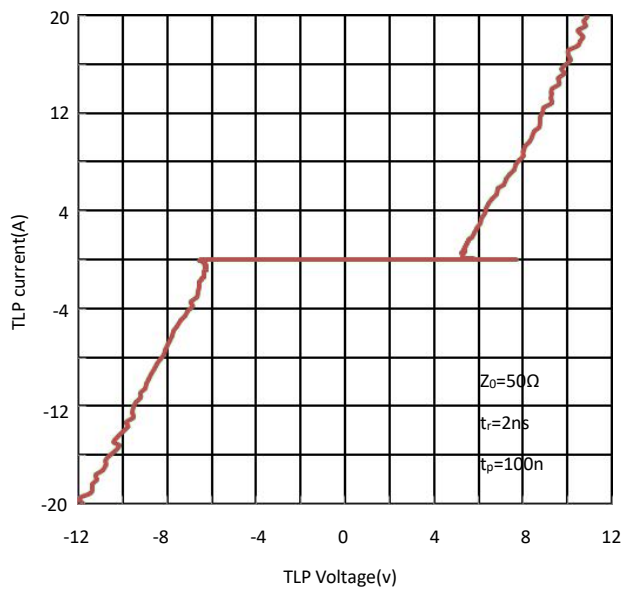
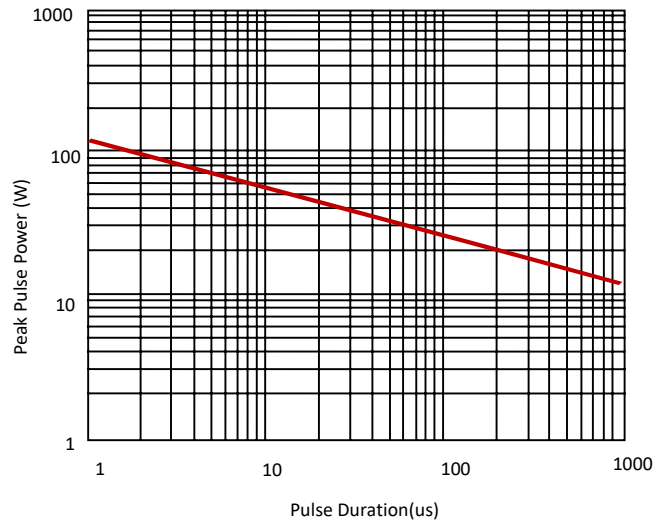
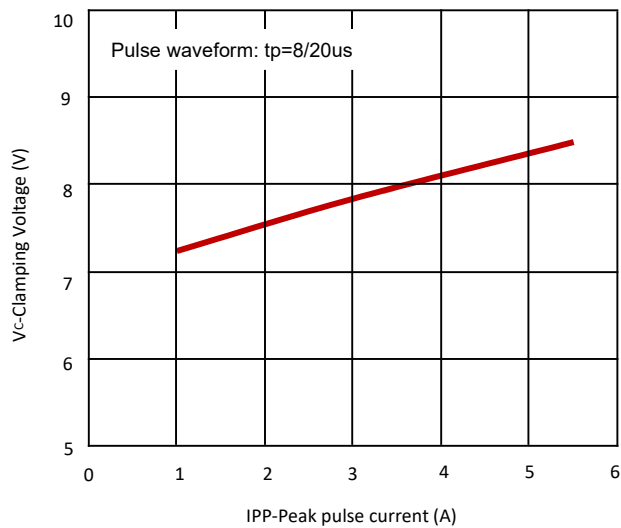
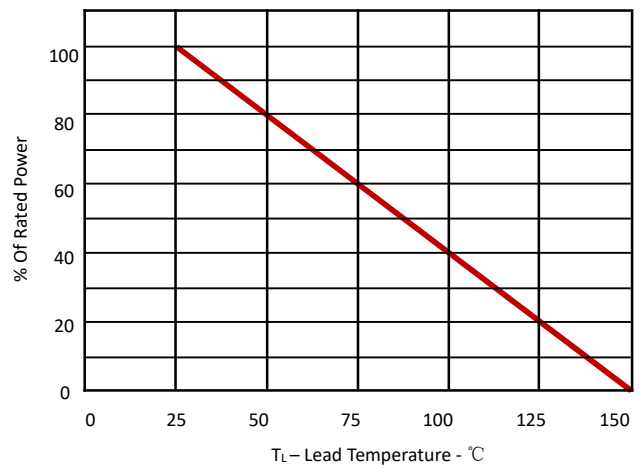
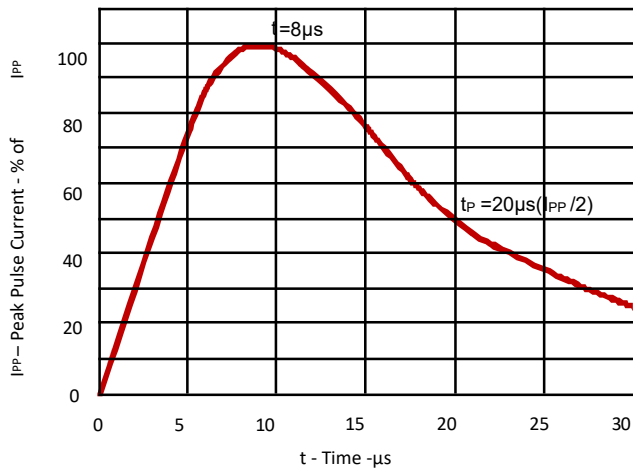
Electrical characteristics per line@25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Peak Reverse Working Voltage	V_{RWM}				5	V
Breakdown Voltage	V_{BR}	$I_T = 1\text{mA}$	5.6	7.0	7.8	V
Reverse Leakage Current	I_R	$V_{RWM} = 5\text{V}$ $T = 25^\circ\text{C}$			1.0	μA
Clamping Voltage	V_{CL}	$I_{PP} = 16\text{A}$ $t_p = 100\text{ns}$		10.5		V
Clamping Voltage	V_C	$I_{PP} = 1\text{A}$		7.5	8.0	V
Clamping Voltage	V_C	$I_{PP} = 3\text{A}$		8.0	9.0	V
Clamping Voltage	V_C	$I_{PP} = 10\text{A}$		8.5	12	V
Junction Capacitance	C_J	$V_R = 0\text{V}$ $f = 1\text{MHz}$		30		pF

Absolute maximum rating@25°C

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu\text{s}$)	P_{PP}	120	W
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{PP}	10	A
Operating Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

Typical Characteristics



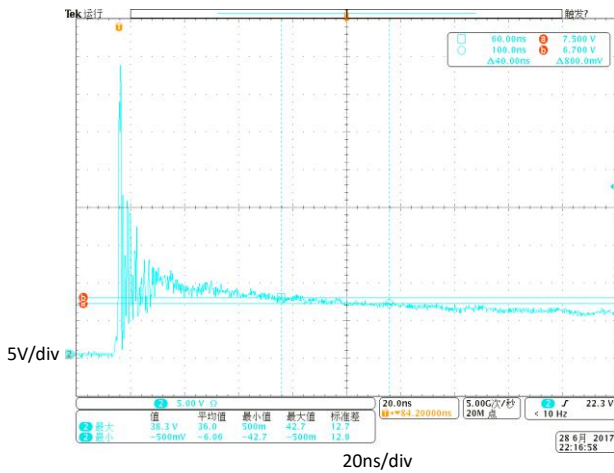


Fig 7. ESD clamping voltage
(IEC61000-4-2 +8KV contact)

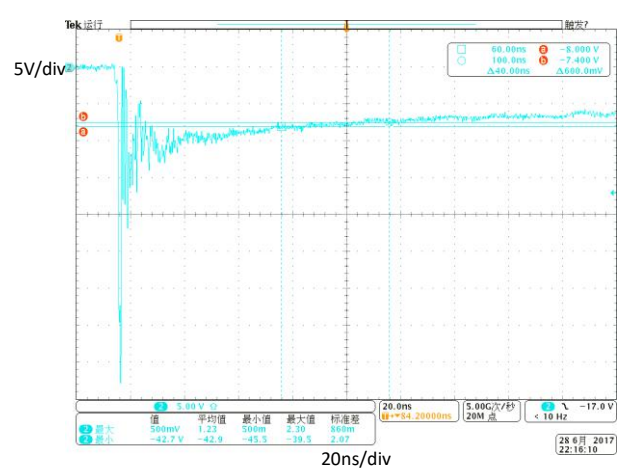
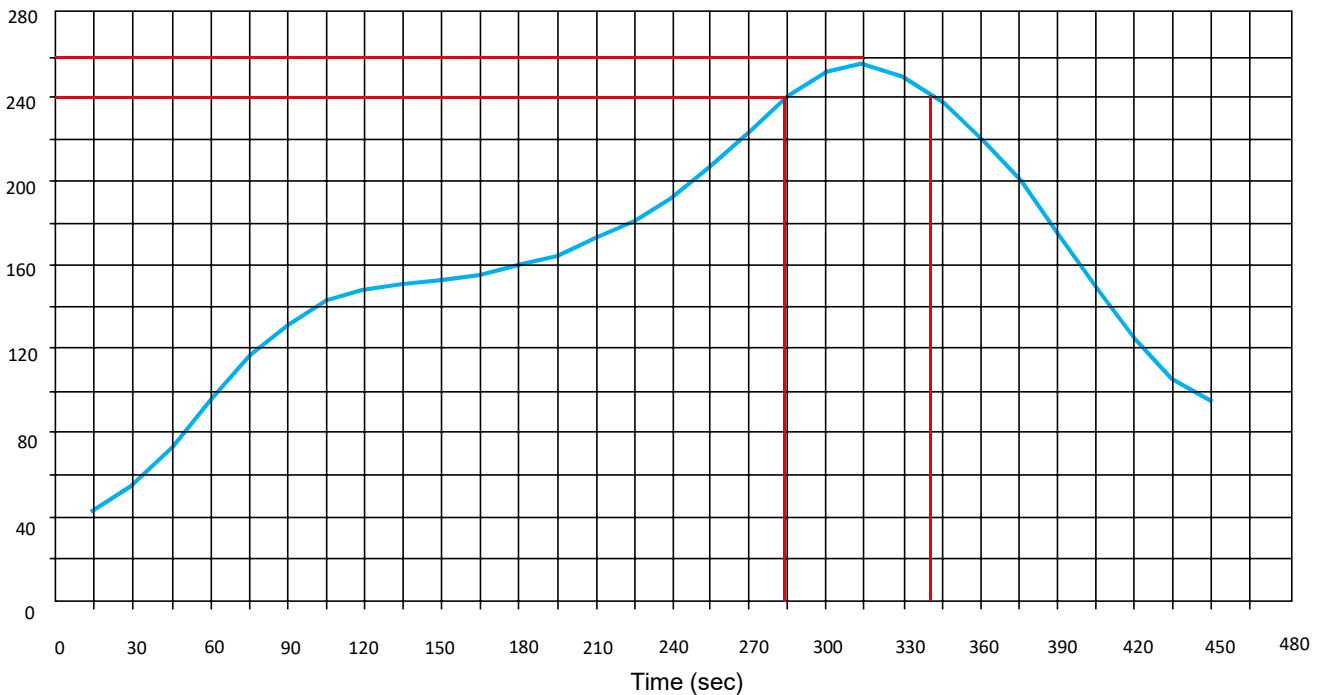


Fig 8. ESD clamping voltage
(IEC61000-4-2-8KV contact)

SolderReflowRecommendation

Peak Temp=257℃, Ramp Rate=0.802deg. °C/sec

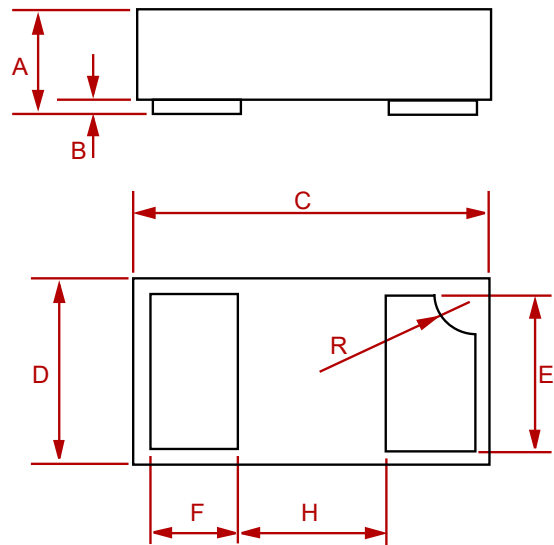


PCB Design

For TVS diodes a low-ohmic and low-inductive path to chassis earth is absolutely mandatory in order to achieve good ESD protection. Novices in the area of ESD protection should take following suggestions to heart:

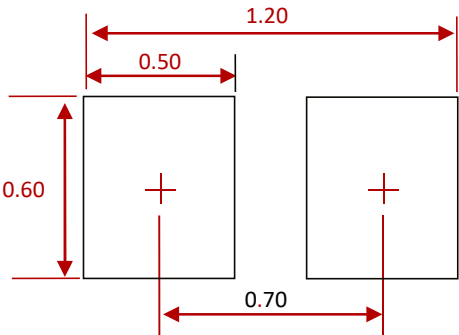
- Do not use stubs, but place the cathode of the TVS diode directly on the signal trace.
- Do not make false economies and save copper for the ground connection.
- Place via holes to ground as close as possible to the anode of the TVS diode.
- Use as many via holes as possible for the ground connection.
- Keep the length of via holes in mind! The longer the more inductance they will have.

PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters	
	MIN	MAX	MIN	MAX
A	0.0125	0.02	0.32	0.52
B	0.000	0.002	0.00	0.05
C	0.037	0.043	0.95	1.080
D	0.022	0.027	0.55	0.680
E	0.016	0.024	0.40	0.60
F	0.008	0.012	0.20	0.30
H	0.015Typ.		0.40Typ.	
R	0.001	0.005	0.05	0.15

Suggested Pad Layout



- NOTES:
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
MSAZ5825-01F	DFN1006	10000

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